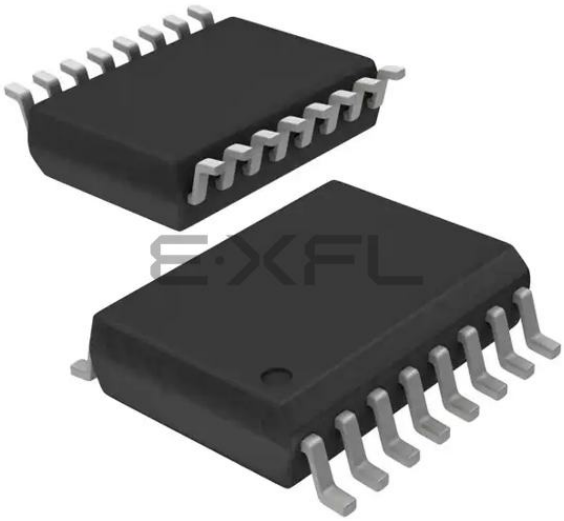

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st7flit19by1m6

DATA EEPROM (Cont'd)

5.7 REGISTER DESCRIPTION

EEPROM CONTROL/STATUS REGISTER (EECSR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	E2LAT	E2PGM

Bits 7:2 = Reserved, forced by hardware to 0.

Bit 1 = **E2LAT** *Latch Access Transfer*
This bit is set by software. It is cleared by hardware at the end of the programming cycle. It can only be cleared by software if the E2PGM bit is cleared.
0: Read mode
1: Write mode

Bit 0 = **E2PGM** *Programming control and status*
This bit is set by software to begin the programming cycle. At the end of the programming cycle, this bit is cleared by hardware.
0: Programming finished or not yet started
1: Programming cycle is in progress

Note: if the E2PGM bit is cleared during the programming cycle, the memory data is not guaranteed

Table 3. DATA EEPROM Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0030h	**EECSR**							E2LAT	E2PGM
	Reset Value	0	0	0	0	0	0	0	0

6 CENTRAL PROCESSING UNIT

6.1 INTRODUCTION

This CPU has a full 8-bit architecture and contains six internal registers allowing efficient 8-bit data manipulation.

6.2 MAIN FEATURES

- 63 basic instructions
- Fast 8-bit by 8-bit multiply
- 17 main addressing modes
- Two 8-bit index registers
- 16-bit stack pointer
- Low power modes
- Maskable hardware interrupts
- Non-maskable software interrupt

6.3 CPU REGISTERS

The six CPU registers shown in Figure 1 are not present in the memory mapping and are accessed by specific instructions.

Accumulator (A)

The Accumulator is an 8-bit general purpose register used to hold operands and the results of the arithmetic and logic calculations and to manipulate data.

Index Registers (X and Y)

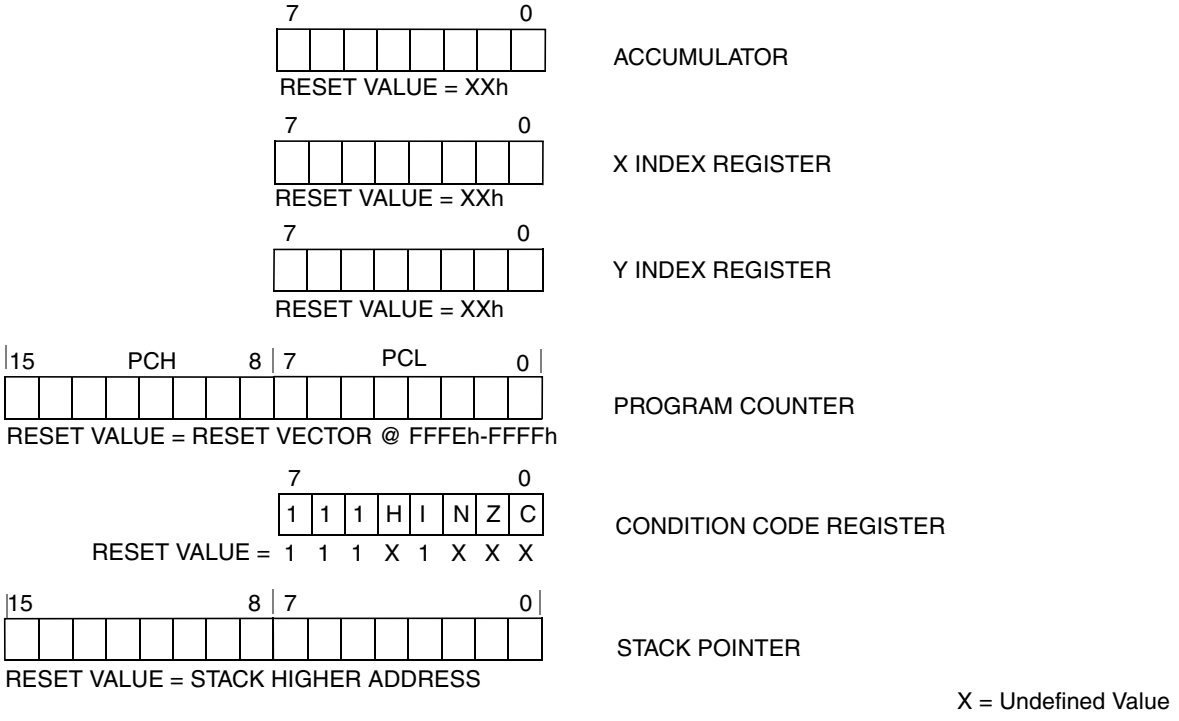
In indexed addressing modes, these 8-bit registers are used to create either effective addresses or temporary storage areas for data manipulation. (The Cross-Assembler generates a precede instruction (PRE) to indicate that the following instruction refers to the Y register.)

The Y register is not affected by the interrupt automatic procedures (not pushed to and popped from the stack).

Program Counter (PC)

The program counter is a 16-bit register containing the address of the next instruction to be executed by the CPU. It is made of two 8-bit registers PCL (Program Counter Low which is the LSB) and PCH (Program Counter High which is the MSB).

Figure 11. CPU Registers



7.3 REGISTER DESCRIPTION

MAIN CLOCK CONTROL/STATUS REGISTER (MCCSR)
Read / Write
Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	MCO	SMS

Bits 7:2 = Reserved, must be kept cleared.

Bit 1 = **MCO** *Main Clock Out enable*
This bit is read/write by software and cleared by hardware after a reset. This bit allows to enable the MCO output clock.
0: MCO clock disabled, I/O port free for general purpose I/O.
1: MCO clock enabled.

Bit 0 = **SMS** *Slow Mode select*
This bit is read/write by software and cleared by hardware after a reset. This bit selects the input clock f_{OSC} or $f_{OSC}/32$.
0: Normal mode ($f_{CPU} = f_{OSC}$
1: Slow mode ($f_{CPU} = f_{OSC}/32$)

RC CONTROL REGISTER (RCCR)
Read / Write
Reset Value: 1111 1111 (FFh)

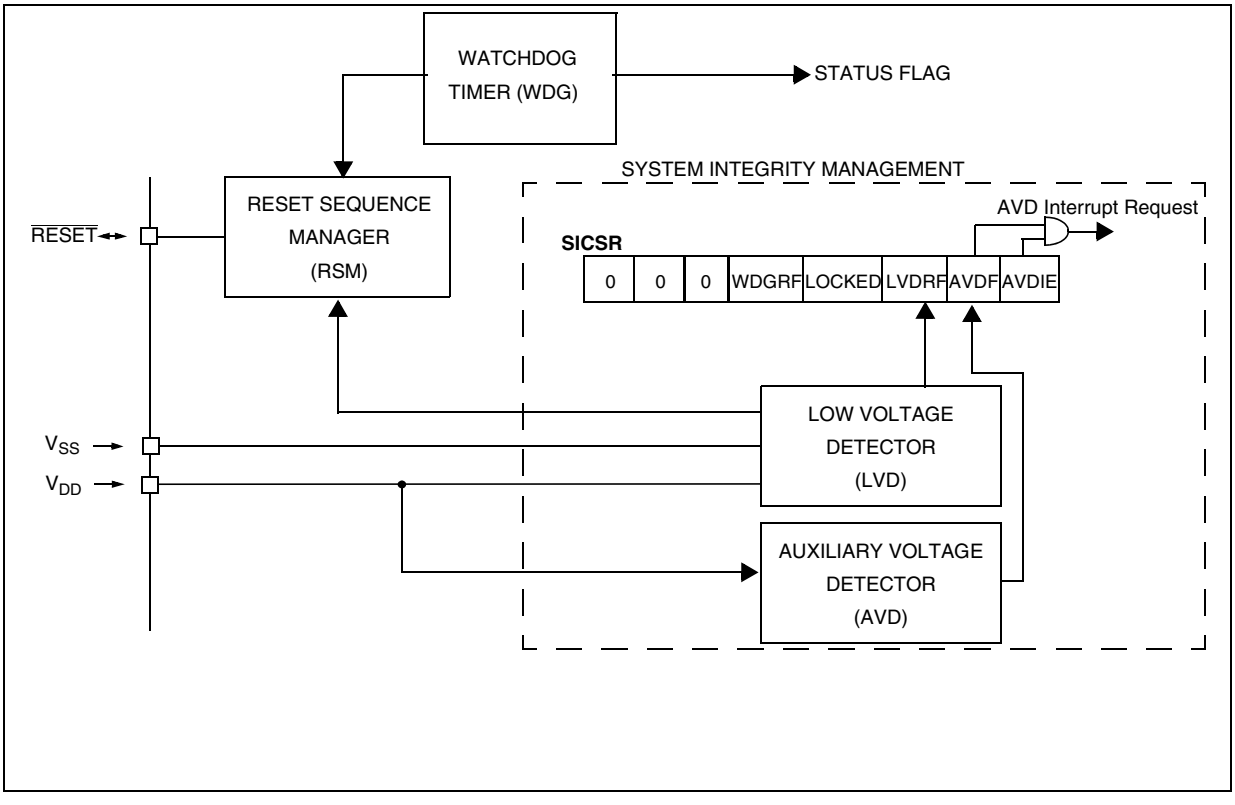
7							0
CR9	CR8	CR7	CR6	CR5	CR4	CR3	CR2

Bits 7:0 = **CR[9:2]** *RC Oscillator Frequency Adjustment Bits*
These bits must be written immediately after reset to adjust the RC oscillator frequency and to obtain an accuracy of 1%. The application can store the correct value for each voltage range in EEPROM and write it to this register at start-up.
00h = maximum available frequency
FFh = lowest available frequency
These bits are used with the CR[1:0] bits in the SICSR register. Refer to section 7.6.4 on page 35.

Note: To tune the oscillator, write a series of different values in the register until the correct frequency is reached. The fastest method is to use a dichotomy starting with 80h.

SYSTEM INTEGRITY MANAGEMENT (Cont'd)

Figure 19. Reset and Supply Management Block Diagram



SYSTEM INTEGRITY MANAGEMENT (Cont'd)

7.6.3 Low Power Modes

Mode	Description
WAIT	No effect on SI. AVD interrupts cause the device to exit from Wait mode.
HALT	The SICSR register is frozen. The AVD remains active.

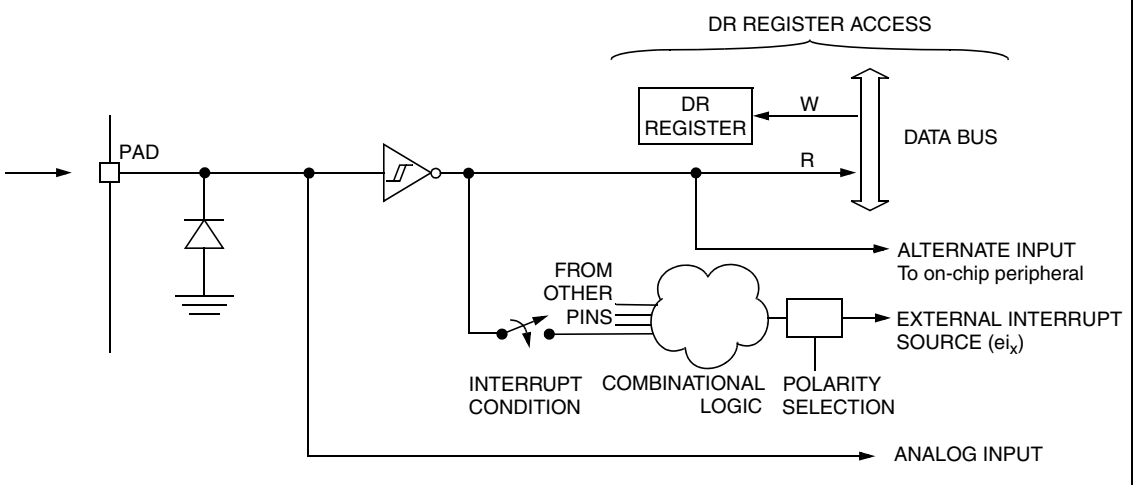
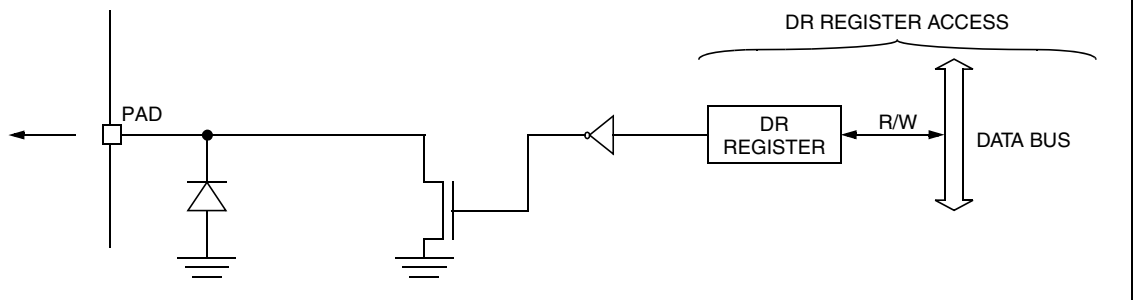
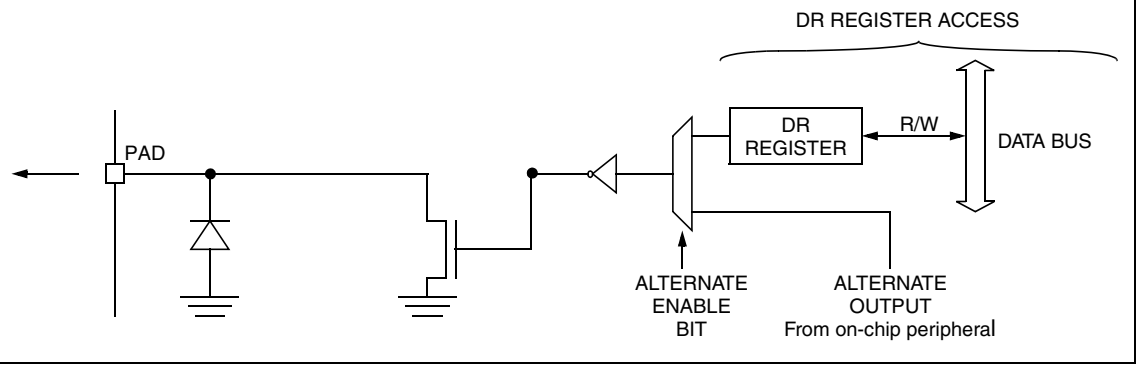
7.6.3.1 Interrupts

The AVD interrupt event generates an interrupt if the corresponding Enable Control Bit (AVDIE) is set and the interrupt mask in the CC register is reset (RIM instruction).

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
AVD event	AVDF	AVDIE	Yes	No

I/O PORTS (Cont'd)

Table 9. I/O Configurations

	Hardware Configuration
INPUT [1]	
OPEN-DRAIN OUTPUT [2]	
PUSH-PULL OUTPUT [2]	

Notes:
1. When the I/O port is in input configuration and the associated alternate function is enabled as an output, reading the DR register will read the alternate function output status.
2. When the I/O port is in output configuration and the associated alternate function is enabled as an input, the alternate function reads the pin status given by the DR register content.

DUAL 12-BIT AUTORELOAD TIMER 4 (Cont'd)

11.2.3.5 Input Capture Mode

The 12-bit ATICR register is used to latch the value of the 12-bit free running upcounter CNTR1 after a rising or falling edge is detected on the ATIC pin. When an input capture occurs, the ICF bit is set and the ATICR register contains the value of the free running upcounter. An IC interrupt is generated if the ICIE bit is set. The ICF bit is reset by reading the ATICRH/ATICRL register when the ICF bit is set. The ATICR is a read only register and always contains the free running upcounter value which corresponds to the most recent input capture. Any further input capture is inhibited while the ICF bit is set.

Figure 43. Block Diagram of Input Capture Mode

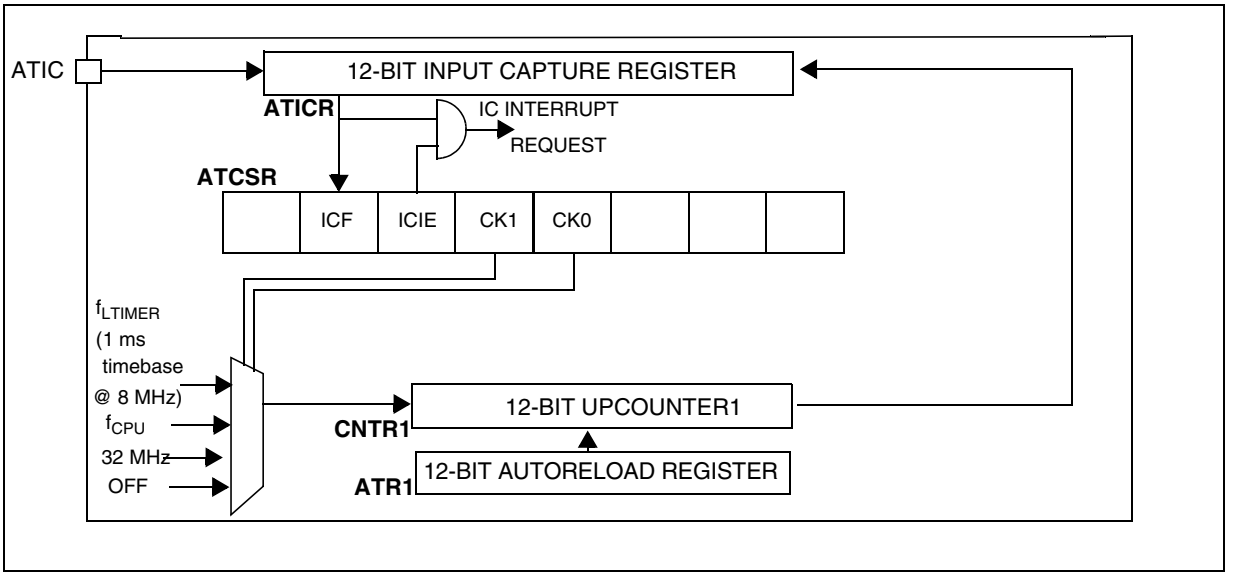
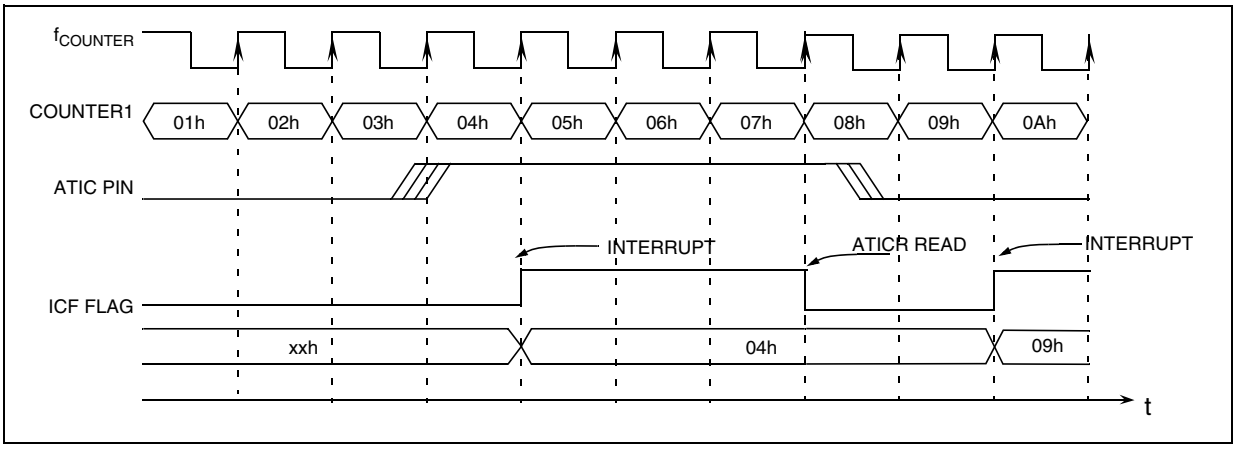


Figure 44. Input Capture timing diagram



DUAL 12-BIT AUTORELOAD TIMER 4 (Cont'd)

11.2.4 Low Power Modes

Mode	Description
WAIT	No effect on AT timer
HALT	AT timer halted.

11.2.5 Interrupts

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt	Exit from Active-Halt
Overflow Event	OVF1	OVIE1	Yes	No	Yes
AT4 IC Event	ICF	ICIE	Yes	No	No
CMP Event	CMPFx	CMPIE	Yes	No	No
Overflow Event2	OVF2	OVIE2	Yes	No	No

Note: The CMP and AT4 IC events are connected to the same interrupt vector.
The OVF event is mapped on a separate vector (see Interrupts chapter).
They generate an interrupt if the enable bit is set in the ATCSR register and the interrupt mask in the CC register is reset (RIM instruction).

LITE TIMER (Cont'd)

Table 15. Lite Timer Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
08	**LTCSR2** Reset Value	0	0	0	0	0	0	TB2IE 0	TB2F 0
09	**LTARR** Reset Value	AR7 0	AR6 0	AR5 0	AR4 0	AR3 0	AR2 0	AR1 0	AR0 0
0A	**LTCNTR** Reset Value	CNT7 0	CNT6 0	CNT5 0	CNT4 0	CNT3 0	CNT2 0	CNT1 0	CNT0 0
0B	**LTCSR1** Reset Value	ICIE 0	ICF x	TB 0	TB1IE 0	TB1F 0	0	0	0
0C	**LTICR** Reset Value	ICR7 0	ICR6 0	ICR5 0	ICR4 0	ICR3 0	ICR2 0	ICR1 0	ICR0 0

SERIAL PERIPHERAL INTERFACE (cont'd)

11.4.4 Clock Phase and Clock Polarity

Four possible timing relationships may be chosen by software, using the CPOL and CPHA bits (See Figure 5).

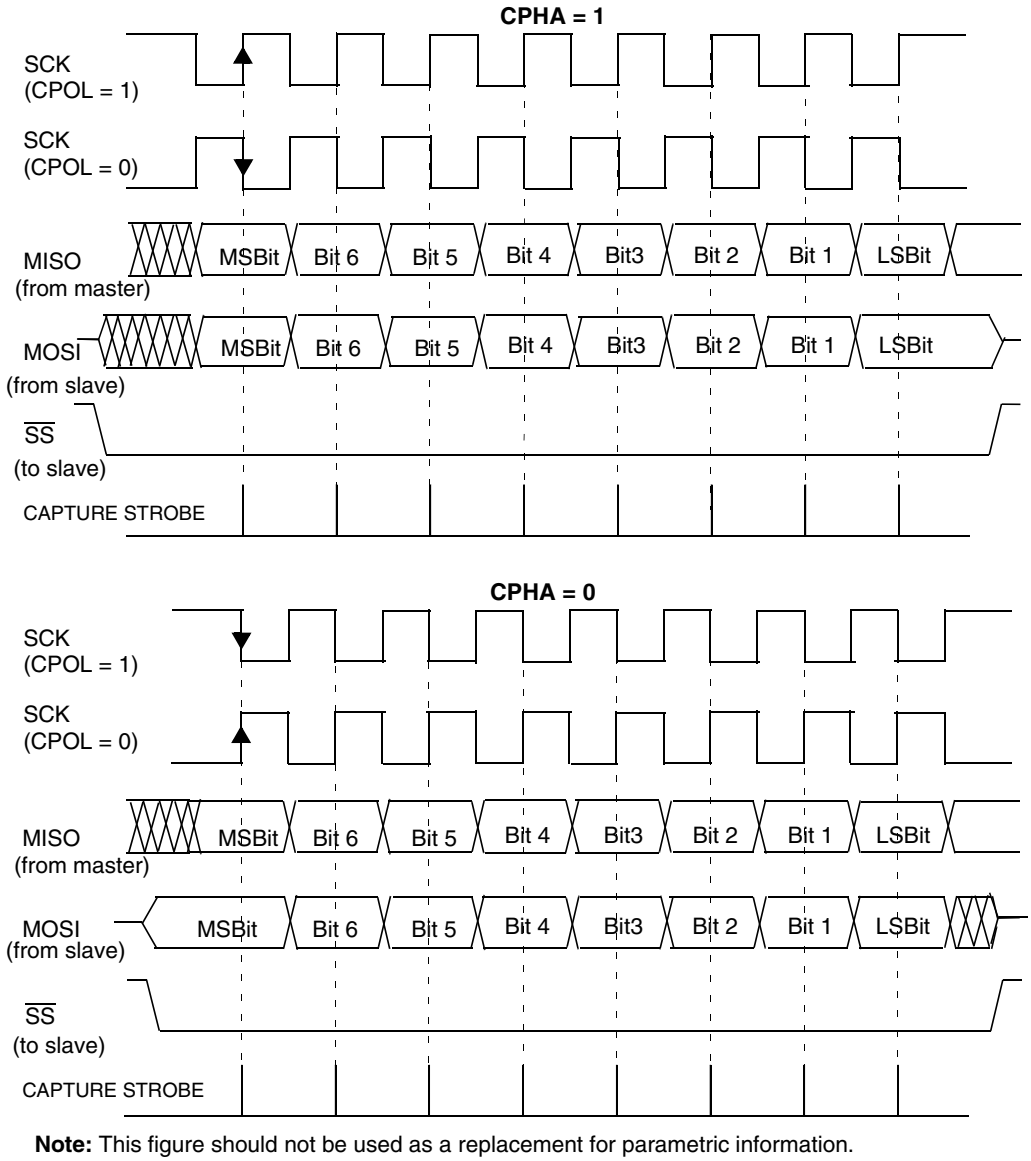
Note: The idle state of SCK must correspond to the polarity selected in the SPICSR register (by pulling up SCK if CPOL = 1 or pulling down SCK if CPOL = 0).

The combination of the CPOL clock polarity and CPHA (clock phase) bits selects the data capture clock edge.

Figure 5 shows an SPI transfer with the four combinations of the CPHA and CPOL bits. The diagram may be interpreted as a master or slave timing diagram where the SCK pin, the MISO pin and the MOSI pin are directly connected between the master and the slave device.

Note: If CPOL is changed at the communication byte boundaries, the SPI must be disabled by resetting the SPE bit.

Figure 57. Data Clock Timing Diagram



Note: This figure should not be used as a replacement for parametric information. Refer to the Electrical Characteristics chapter.

11.5 10-BIT A/D CONVERTER (ADC)

11.5.1 Introduction

The on-chip Analog to Digital Converter (ADC) peripheral is a 10-bit, successive approximation converter with internal sample and hold circuitry. This peripheral has up to 7 multiplexed analog input channels (refer to device pin out description) that allow the peripheral to convert the analog voltage levels from up to 7 different sources.

The result of the conversion is stored in a 10-bit Data Register. The A/D converter is controlled through a Control/Status Register.

11.5.2 Main Features

- 10-bit conversion
- Up to 7 channels with multiplexed input
- Linear successive approximation
- Data register (DR) which contains the results
- Conversion complete status flag
- On/off bit (to reduce consumption)

The block diagram is shown in Figure 60.

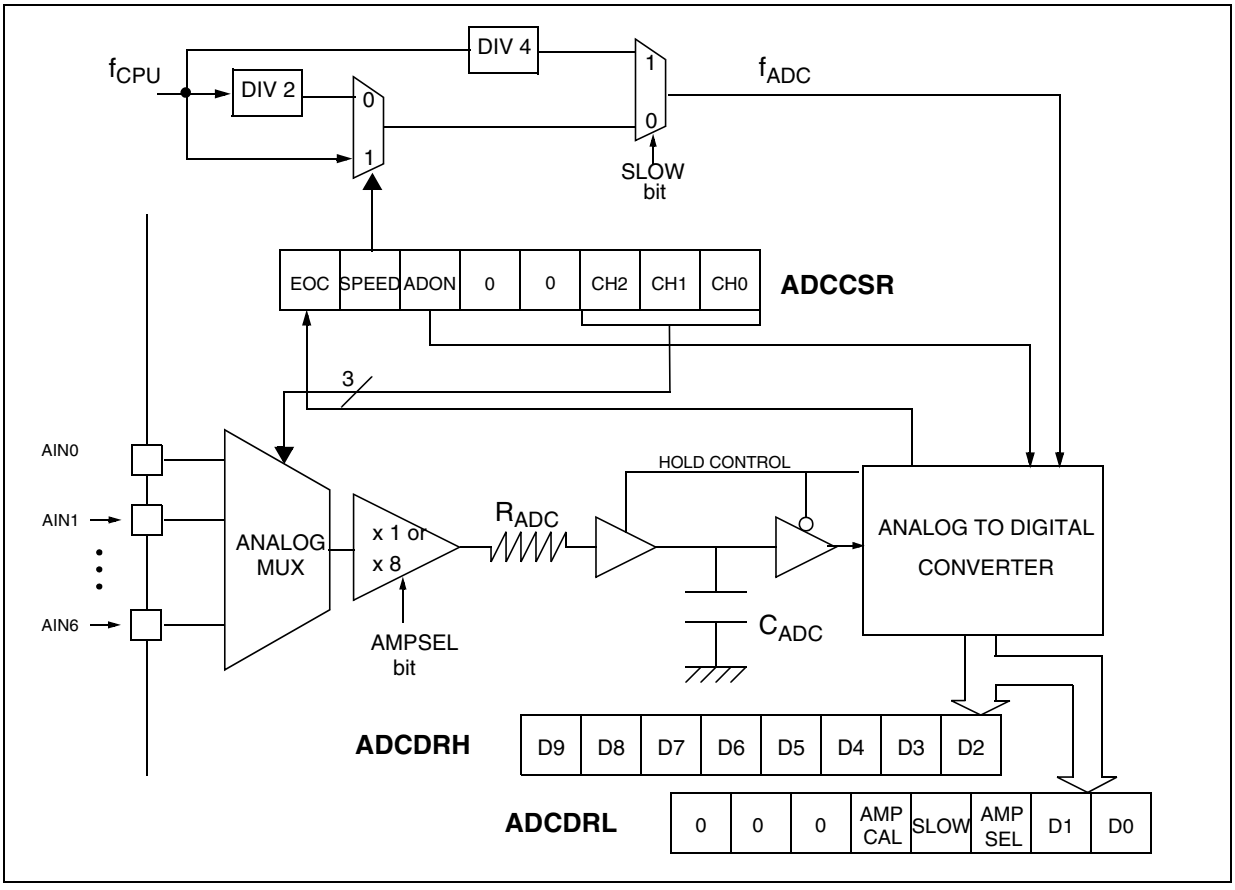
11.5.3 Functional Description

11.5.3.1 Analog Power Supply

V_{DDA} and V_{SSA} are the high and low level reference voltage pins. In some devices (refer to device pin out description) they are internally connected to the V_{DD} and V_{SS} pins.

Conversion accuracy may therefore be impacted by voltage drops and noise in the event of heavily loaded or badly decoupled power supply lines.

Figure 60. ADC Block Diagram



ANALOG COMPARATOR (Cont'd)

Bit 4 = **CMPIF** *Comparator Interrupt Flag*

This bit is set by hardware when interrupt is generated at the rising edge (CINV = 0) or falling edge (CINV = 1) of comparator output. This bit is cleared by reading the CMPCR register. Writing to this bit does not change the value.
0 : Comparator interrupt flag cleared
1 : Comparator interrupt flag set and can generate interrupt if CMPIE is set.

Bit 3 : **CMPIE** *Comparator Interrupt Enable*

This bit is set or reset by software and cleared by hardware reset. This bit enables or disables the interrupt generation depending on interrupt flag
0: Interrupt not generated
1: Interrupt generated if interrupt flag is set

Note:

This bit should be set to enable interrupt only after the comparator has been switched ON, i.e. when CMPON is set.

Once CMPON bit is set, it is recommended to wait the specified stabilization time before setting CMPIE bit in order to avoid a spurious interrupt (see section 13.12 on page 143).

Bit 2 : **CMP** *Comparator Output*

This bit is set or reset by software and cleared by hardware reset. It stores the value of comparator output.

Bit 1 = **COUT** *Comparator Output Enable on Port*
This bit is set or cleared by software. When this bit is set, the comparator output is available on PA7 port.
0 : Comparator output not connected to PA7
1 : Comparator output connected to PA7

Bit 0 : **CMPON** *Comparator ON/OFF*
This bit is set or cleared by software and reset by hardware reset. This bit is used to switch ON/OFF the comparator, internal voltage reference and current bias which provides 4µA current to both.
0: Comparator, Internal Voltage Reference, Bias OFF (in power-down state).
1: Comparator, Internal Voltage Reference, Bias ON

Note: For the comparator interrupt generation, it takes 250ns delay from comparator output change to rising or falling edge of interrupt generated.

Table 21. Analog Comparator Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
002Ch	**VREFCR**	VCEXT	VCBGR	VR3	VR2	VR1	VR0	-	-
	Reset Value	0	0	0	0	0	0	0	0
002Dh	**CMPCR**	CHYST	-	CINV	CMPIF	CMPIE	CMP	COUT	CMPON
	Reset value	1	0	0	0	0	0	0	0

13 ELECTRICAL CHARACTERISTICS

13.1 PARAMETER CONDITIONS

Unless otherwise specified, all voltages are referred to V_{SS}.

13.1.1 Minimum and Maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A=25°C and T_A=$T_A$max (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3Σ).

13.1.2 Typical values

Unless otherwise specified, typical data are based on T_A=25°C, V_{DD}=5V (for the 4.5V≤V_{DD}≤5.5V voltage range) and V_{DD}=3.3V (for the 3V≤V_{DD}≤3.6V voltage range). They are given only as design guidelines and are not tested.

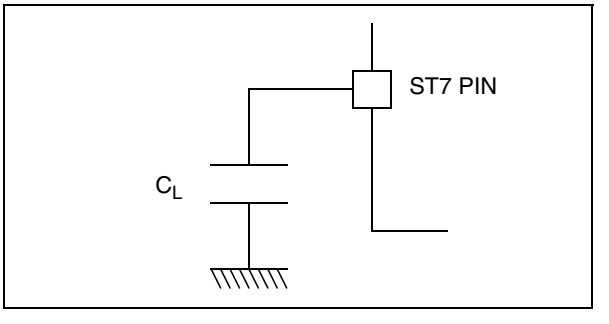
13.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

13.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in Figure 63.

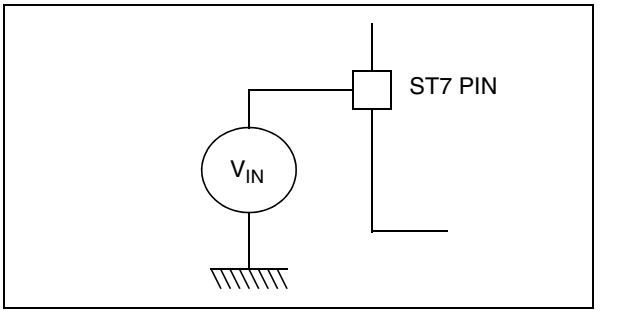
Figure 63. Pin loading conditions



13.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in Figure 64.

Figure 64. Pin input voltage



13.2 ABSOLUTE MAXIMUM RATINGS

Stresses above those listed as “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.2.1 Voltage Characteristics

Symbol	Ratings	Maximum value	Unit
V_{DD} - V_{SS}	Supply voltage	7.0	V
V_{IN}	Input voltage on any pin [1) & 2)]	V_{SS}-0.3 to V_{DD}+0.3	
$V_{ESD(HBM)}$	Electrostatic discharge voltage (Human Body Model)	see section 13.7.3 on page 128	
$V_{ESD(MM)}$	Electrostatic discharge voltage (Machine Model)		

13.2.2 Current Characteristics

Symbol	Ratings	Maximum value	Unit
I_{VDD}	Total current into V_{DD} power lines (source) [3)]	75	mA
I_{VSS}	Total current out of V_{SS} ground lines (sink) [3)]	150	
I_{IO}	Output current sunk by any standard I/O and control pin	20	
	Output current sunk by any high sink I/O pin	40	
	Output current source by any I/Os and control pin	- 25	
$I_{INJ(PIN)}$ [2) & 4)]	Injected current on ISPSEL pin	± 5	
	Injected current on $\overline{RESET}$ pin	± 5	
	Injected current on OSC1 and OSC2 pins	± 5	
	Injected current on PB0 pin [5)]	+5	
	Injected current on any other pin [6)]	± 5	
$\Sigma I_{INJ(PIN)}$ [2)]	Total injected current (sum of all I/O and control pins) [6)]	± 20	

13.2.3 Thermal Characteristics

Symbol	Ratings	Value	Unit
T_{STG}	Storage temperature range	-65 to +150	°C
T_J	Maximum junction temperature (see Table 24, “THERMAL CHARACTERISTICS,” on page 147)		

Notes:

1. Directly connecting the $\overline{RESET}$ and I/O pins to V_{DD} or V_{SS} could damage the device if an unintentional internal reset is generated or an unexpected change of the I/O configuration occurs (for example, due to a corrupted program counter). To guarantee safe operation, this connection has to be done through a pull-up or pull-down resistor (typical: 4.7kΩ for $\overline{RESET}$, 10kΩ for I/Os). Unused I/O pins must be tied in the same way to V_{DD} or V_{SS} according to their reset configuration.
2. $I_{INJ(PIN)}$ must never be exceeded. This is implicitly insured if V_{IN} maximum is respected. If V_{IN} maximum cannot be respected, the injection current must be limited externally to the $I_{INJ(PIN)}$ value. A positive injection is induced by $V_{IN}>V_{DD}$ while a negative injection is induced by $V_{IN}<V_{SS}$. For true open-drain pads, there is no positive injection current, and the corresponding V_{IN} maximum must always be respected
3. All power (V_{DD}) and ground (V_{SS}) lines must always be connected to the external supply.
4. Negative injection disturbs the analog performance of the device. In particular, it induces leakage currents throughout the device including the analog inputs. To avoid undesirable effects on the analog functions, care must be taken:
- Analog input pins must have a negative injection less than 0.8 mA (assuming that the impedance of the analog voltage is lower than the specified limits)
- Pure digital pins must have a negative injection less than 1.6mA. In addition, it is recommended to inject the current as far as possible from the analog input pins.
5. No negative current injection allowed on PB0 pin.
6. When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterisation with $\Sigma I_{INJ(PIN)}$ maximum current injection on four I/O port pins of the device.

13.3.3 Operating Conditions with Low Voltage Detector (LVD)

13.3.3.1 Operating Conditions with LVD at T_A = -40 to 125°C, unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IT+(LVD)}$	Reset release threshold (V_{DD} rise)	High Threshold Med. Threshold Low Threshold	3.80 3.20 2.65	4.20 3.55 2.85	4.60 3.90 3.10	V
$V_{IT-(LVD)}$	Reset generation threshold (V_{DD} fall)	High Threshold Med. Threshold Low Threshold	3.70 3.10 2.50	4.00 3.35 2.70	4.35 3.70 2.90	
V_{hys}	LVD voltage threshold hysteresis	$V_{IT+(LVD)}$-$V_{IT-(LVD)}$		200		mV
Vt_{POR}	V_{DD} rise time rate [1)2)]				100	ms/V
$t_{g(VDD)}$	Filtered glitch delay on V_{DD} [1)]	Not detected by the LVD		150		ns
$I_{DD(LVD)}$	LVD/AVD current consumption			200		µA

Notes:

1. The V_{DD} rise time rate condition is needed to insure a correct device power-on and LVD reset. Not tested in production.

2. Use of LVD with capacitive power supply: with this type of power supply, if power cuts occur in the application, it is recommended to pull V_{DD} down to 0V to ensure optimum restart conditions. Refer to circuit example in Figure 106 on page 136 and note 4.

OPERATING CONDITIONS (Cont'd)

The RC oscillator and PLL characteristics are temperature-dependent and are grouped in four tables.

13.3.5.1 Devices with '"6" or "3"order code suffix (tested for T_A = -40 to +125°C) @ V_{DD} = 5V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{RC}	Internal RC oscillator frequency [1]	RCCR = FF (reset value), T_A=25°C,V_{DD}=5V		700		kHz
		RCCR = RCCR0[2],T_A=25°C,V_{DD}=5V	992	1000	1008	
ACC_{RC}	Accuracy of Internal RC oscillator with RCCR=RCCR0[2]	T_A=25°C,V_{DD}=5V	-0.8		+0.8	%
		T_A=25°C, V_{DD}=4.5 to 5.5V[3]	-1		+1	%
		T_A=25°C to +85°C,V_{DD}=5V	-3		+3	%
		T_A=25°C to +85°C,V_{DD}=4.5 to 5.5V[3]	-3.5		+3.5	%
		T_A=85°C to +125°C,V_{DD}=5V	-3.5		+5	%
		T_A=85°C to +125°C,V_{DD}=4.5 to 5.5V[3]	-3.5		+6	%
		T_A=-40 to +25°C, V_{DD}=5V[3]	-3		+7	%
$I_{DD(RC)}$	RC oscillator current consumption	T_A=25°C,V_{DD}=5V		600[3]		µA
$t_{su(RC)}$	RC oscillator setup time	T_A=25°C,V_{DD}=5V			10[2]	µs
f_{PLL}	x8 PLL input clock			1[3]		MHz
t_{LOCK}	PLL Lock time[5]			2		ms
t_{STAB}	PLL Stabilization time[5]			4		ms
ACC_{PLL}	x8 PLL Accuracy	f_{RC} = 1MHz@T_A=25°C,V_{DD}=4.5 to 5.5V		0.1[4]		%
		f_{RC} = 1MHz@T_A=-40 to +85°C,V_{DD}=5V		0.1[4]		%
$t_{w(JIT)}$	PLL jitter period [6]	f_{RC} = 1MHz		120		µs
JIT_{PLL}	PLL jitter ($\Delta f_{CPU}/f_{CPU}$)			1[7]		%
$I_{DD(PLL)}$	PLL current consumption	T_A=25°C		600[3]		µA

Notes:

1. If the RC oscillator clock is selected, to improve clock stability and frequency accuracy, it is recommended to place a decoupling capacitor, typically 100nF, between the V_{DD} and V_{SS} pins as close as possible to the ST7 device.

2. See "INTERNAL RC OSCILLATOR ADJUSTMENT" on page 23

3. Data based on characterization results, not tested in production

4. Averaged over a 4ms period. After the LOCKED bit is set, a period of t_{STAB} is required to reach ACC_{PLL} accuracy.

5. After the LOCKED bit is set ACC_{PLL} is max. 10% until t_{STAB} has elapsed. See Figure 13 on page 24.

6. This period is the phase servo loop period. During this period, the frequency remains unchanged.

7. Guaranteed by design.

13.6 MEMORY CHARACTERISTICS

T_A = -40°C to 125°C, unless otherwise specified

13.6.1 RAM and Hardware Registers

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RM}	Data retention mode [1]	HALT mode (or RESET)	1.6			V

13.6.2 FLASH Program Memory

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	Operating voltage for Flash write/erase	Refer to operating range of V_{DD} with T_A, section 13.3.1 on page 112	2.7		5.5	V
t_{prog}	Programming time for 1~32 bytes [2]	T_A=–40 to +125°C		5	10	ms
	Programming time for 1.5 kBytes	T_A=+25°C		0.24	0.48	s
t_{RET}	Data retention [4]	T_A=+55°C[3]	20			years
N_{RW}	Write erase cycles	T_A=+25°C	10K			cycles
I_{DD}	Supply current [6]	Read / Write / Erase modes f_{CPU} = 8MHz, V_{DD} = 5.5V			2.6	mA
		No Read/No Write Mode			100	µA
		Power down mode / HALT		0	0.1	µA

13.6.3 EEPROM Data Memory

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	Operating voltage for EEPROM write/erase	Refer to operating range of V_{DD} with T_A, section 13.3.1 on page 112	2.7		5.5	V
t_{prog}	Programming time for 1~32 bytes	T_A=–40 to +125°C		5	10	ms
t_{ret}	Data retention [4]	T_A=+55°C [3]	20			years
N_{RW}	Write erase cycles	T_A=+25°C	300K			cycles

Notes:

1. Minimum V_{DD} supply voltage without losing data stored in RAM (in HALT mode or under RESET) or in hardware registers (only in HALT mode). Guaranteed by construction, not tested in production.

2. Up to 32 bytes can be programmed at a time.

3. The data retention time increases when the T_A decreases.

4. Data based on reliability test results and monitored in production.

5. Data based on characterization results, not tested in production.

6. Guaranteed by Design. Not tested in production.

COMMUNICATION INTERFACE CHARACTERISTICS (Cont'd)

Figure 108. SPI Slave Timing Diagram with CPHA=1 [1)]

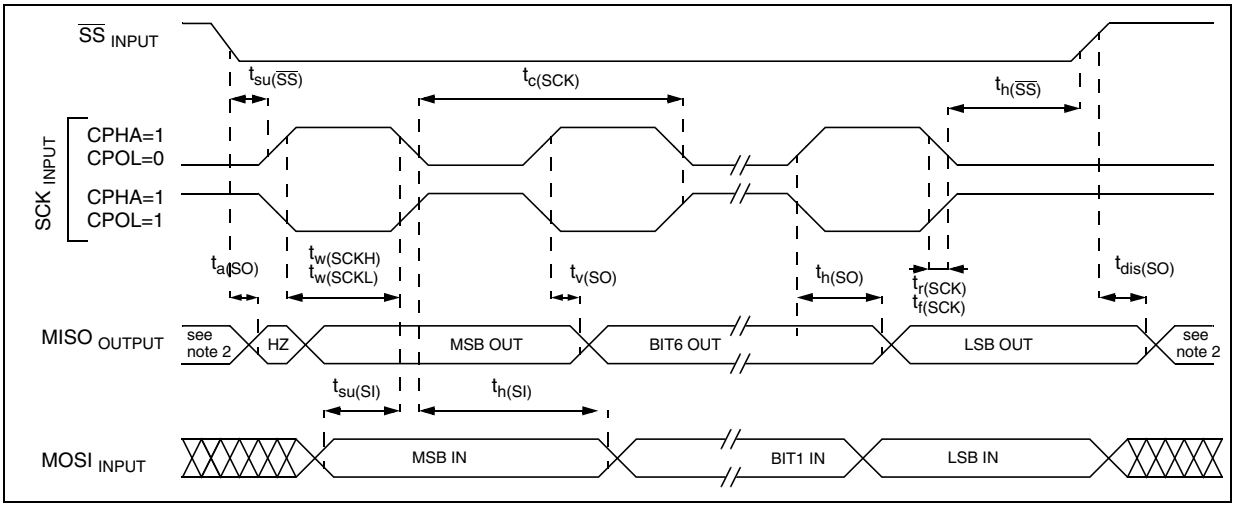
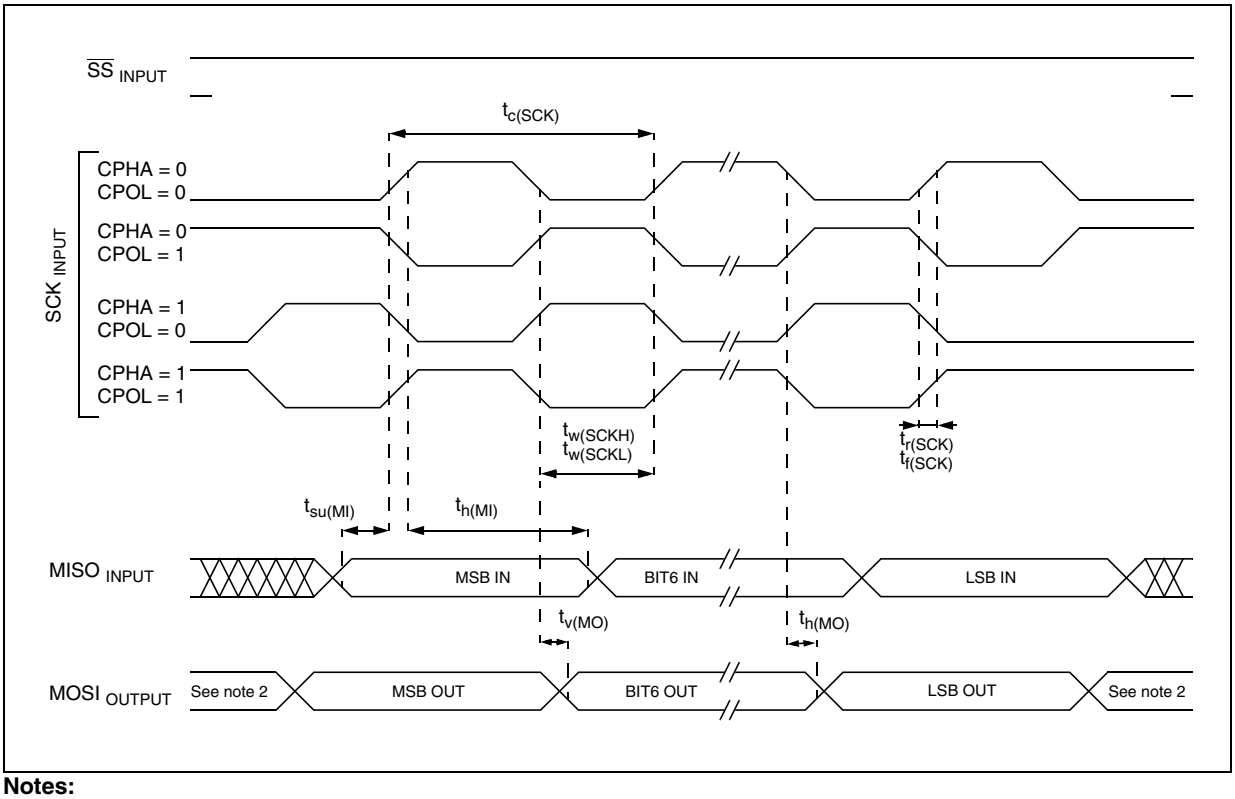


Figure 109. SPI Master Timing Diagram [1)]



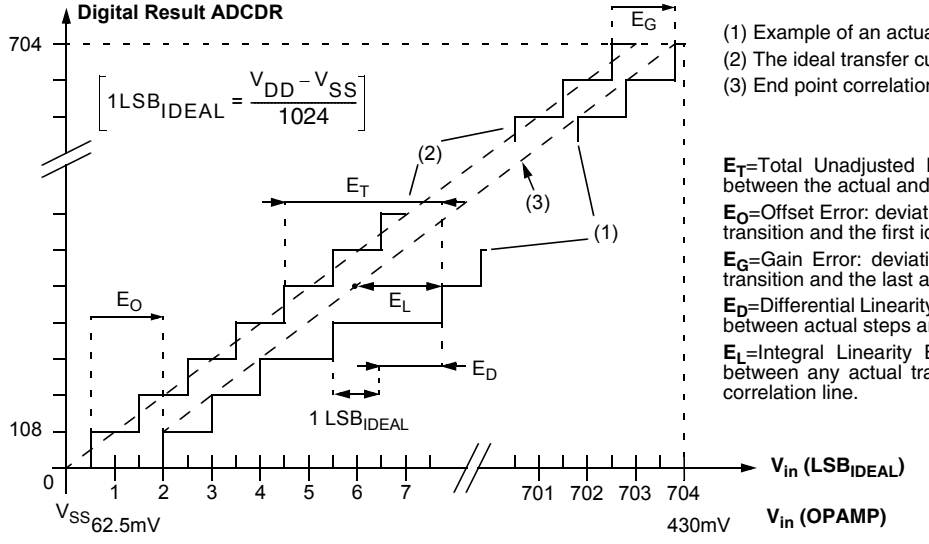
Notes:

1. Measurement points are done at CMOS levels: $0.3xV_{DD}$ and $0.7xV_{DD}$.

2. When no communication is on-going the data output line of the SPI (MOSI in master mode, MISO in slave mode) has its alternate function capability released. In this case, the pin status depends of the I/O port configuration.

ADC CHARACTERISTICS (Cont'd)

Figure 112. ADC Accuracy Characteristics with amplifier enabled



(1) Example of an actual transfer curve
(2) The ideal transfer curve
(3) End point correlation line

E_T=Total Unadjusted Error: maximum deviation between the actual and the ideal transfer curves.

E_O=Offset Error: deviation between the first actual transition and the first ideal one.

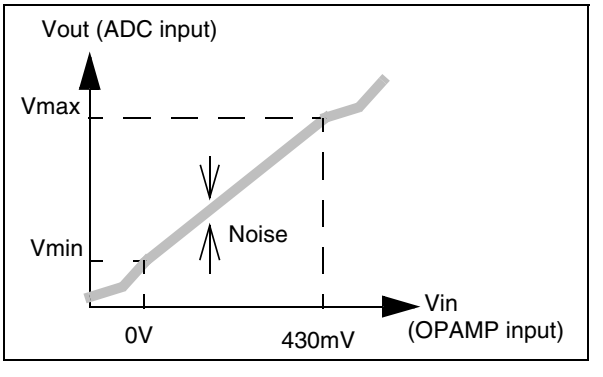
E_G=Gain Error: deviation between the last ideal transition and the last actual one.

E_D=Differential Linearity Error: maximum deviation between actual steps and the ideal one.

E_L=Integral Linearity Error: maximum deviation between any actual transition and the end point correlation line.

Note:

1. When the AMPSEL bit in the ADCDRL register is set, it is mandatory that f_{ADC} be less than or equal to 2 MHz. (if f_{CPU}=8MHz. then SPEED=0, SLOW=1).



13.12 ANALOG COMPARATOR CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
V_{DDA}	Supply range		4.5		5.5	V
V_{IN}	Comparator input voltage range		0		V_{DDA}	V
Temp	Temperature range		-40		125	°C
V_{offset}	Comparator offset error			20		mV
$I_{DD(CMP)}$	Analog Comparator Consumption			120		µA
	Analog Comparator Consumption during power-down			200		pA
t_{propag}	Comparator propagation delay			40		ns
$t_{startup}$	Startup filter duration			500[2]		ns
t_{stab}	Stabilisation time			500		ns

13.13 PROGRAMMABLE INTERNAL VOLTAGE REFERENCE CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
V_{DDA}	Supply range		4	5	5.5	V
Temp	Temperature range		-40	27	125	°C
$I_{DD(VOLTREF)}$	Internal Voltage Reference Consumption			50		µA
	Internal Voltage Reference Consumption during power-down			200		pA
$t_{startup}$	Startup duration			1[2]		µs

13.14 CURRENT BIAS CHARACTERISTICS (for Comparator and Internal Voltage Reference)

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
V_{DDA}	Supply range		4.5	5	5.5	V
Temp	Temperature range		-40	27	125	°C
IDD (Bias)	Bias Consumption in run mode			50		µA
	Bias Consumption during power-down			36		pA
$t_{startup}$	Startup time			1[2]		µs

Notes:

1. Unless otherwise specified, typical data are based on T_A=25°C and V_{DD}-V_{SS}=5V. They are given only as design guidelines and are not tested.

2. Since startup time for internal voltage reference and bias is 1 µs, comparator correct output should not be expected before 1 µs during startup.